

## Switch-mode<sup>™</sup> Power Rectifiers MBR1035, MBR1045

#### **Features and Benefits**

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175 °C Operating Junction Temperature
- 10 A Total
- Pb-Free Packages are Available\*

#### **Applications**

- Power Supply-Output Rectification
- Power Management
- Instrumentation

#### **Mechanical Characteristics**

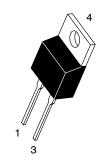
- · Case: Epoxy, Molded
- Epoxy Meets UL 94, V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperatures for Soldering Purposes: 260 °C Max. for 10 Seconds
- ESD Rating: Human Body Model 3B Machine Model C

# SCHOTTKY BARRIER RECTIFIERS 10 AMPERES 35 to 45 VOLTS

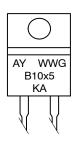


TO-220AC CASE 221B

**PLASTIC** 



#### MARKING DIAGRAM



= Assembly Location

Y = Year

WW = Work Week

G = Pb-Free Package

B10x5 = Device Code

x = 3 or 4

KA = Diode Polarity

#### **ORDERING INFORMATION**

Device	Package	Shipping
MBR1045G	TO-220	50 Units/Rail
	(Pb-Free)	

#### **DISCONTINUED** (Note 1)

MBR1035	TO-220	50 Units/Rail
MBR1035G	TO-220 (Pb-Free)	50 Units/Rail
MBR1045	TO-220	50 Units/Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <a href="https://example.com/BRD8011/D">BRD8011/D</a>.

 DISCONTINUED: This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, <u>SOLDERRM/D</u>

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage	V <sub>RRM</sub> V <sub>RWM</sub>		V
DC Blocking Voltage MBR1035 MBR1045	V <sub>R</sub>	35 45	
Average Rectified Forward Current (T <sub>C</sub> = 135 °C, Per Device)		10	Α
Peak Repetitive Forward Current, (Square Wave, 20 kHz, T <sub>C</sub> = 135 °C)	I <sub>FRM</sub>	10	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	150	Α
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I <sub>RRM</sub>	1.0	Α
Storage Temperature Range		-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +175	°C
Voltage Rate of Change (Rated V <sub>R</sub> )		10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS

Characteristic	Conditions	Symbol	Max	Unit
Maximum Thermal Resistance, Junction-to-Case	Min. Pad	$R_{\theta JC}$	2.0	°C/W
Maximum Thermal Resistance, Junction-to-Ambient	Min. Pad	$R_{\theta JA}$	60	

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Min	Typical	Max	Unit
Instantaneous Forward Voltage (Note 2) ( $i_F$ = 10 Amps, $T_j$ = 125 °C) ( $i_F$ = 20 Amps, $T_j$ = 125 °C) ( $i_F$ = 20 Amps, $T_j$ = 25 °C)	v <sub>F</sub>	- - -	0.55 0.67 0.78	0.57 0.72 0.84	V
Instantaneous Reverse Current (Note 2) (Rated dc Voltage, Tj = 125 °C) (Rated dc Voltage, Tj = 25 °C)	i <sub>R</sub>	- -	5.3 0.008	15 0.1	mA

<sup>2.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

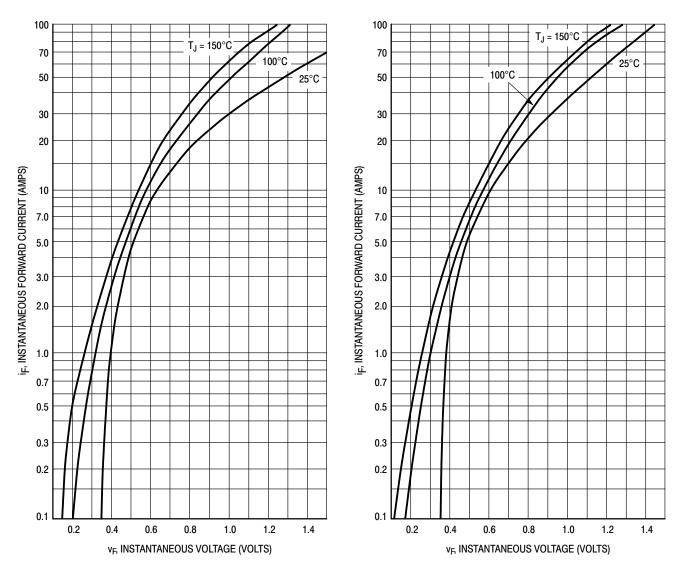
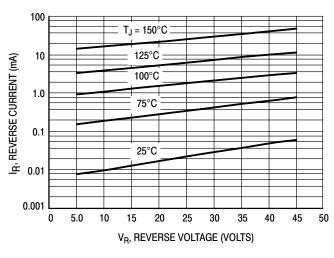


Figure 1. Maximum Forward Voltage

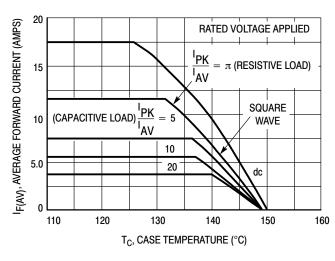
Figure 2. Typical Forward Voltage



200 IFSM, PEAK HALF-WAVE CURRENT (AMPS) 100 70 50 30 20 70 1.0 2.0 3.0 5.0 7.0 10 30 50 100 NUMBER OF CYCLES AT 60 Hz

Figure 3. Maximum Reverse Current

Figure 4. Maximum Surge Capability



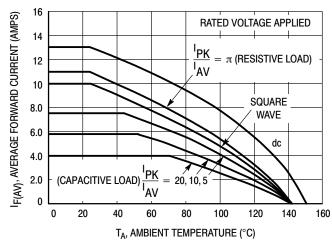
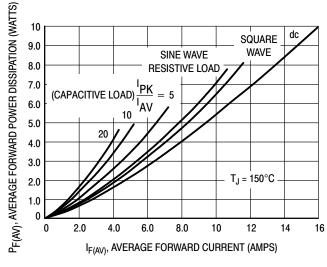


Figure 5. Current Derating, Infinite Heatsink

Figure 6. Current Derating,  $R_{\theta JA} = 16^{\circ}C/W$ 



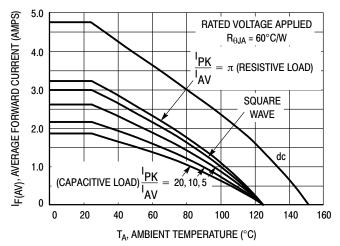


Figure 7. Forward Power Dissipation

Figure 8. Current Derating, Free Air

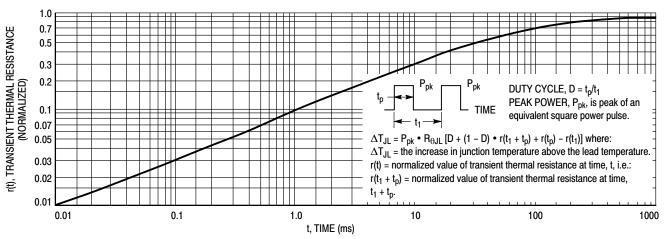


Figure 9. Thermal Response

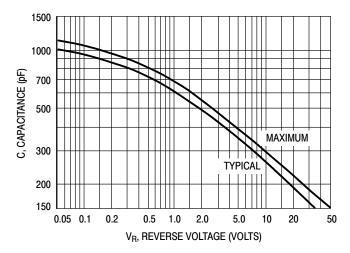


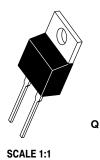
Figure 10. Capacitance

#### **REVISION HISTORY**

Revision	Description of Changes	Date
9	MBR1035, MBR1035G, MBR1045 OPN Marked as Discontinued + Rebranded the Data Sheet to <b>onsemi</b> format	7/9/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.





TO-220, 2-LEAD CASE 221B-04 ISSUE F

**DATE 12 APR 2013** 

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.595	0.620	15.11	15.75
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.82
D	0.025	0.039	0.64	1.00
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
Н	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

STYLE 1: PIN 1. CATHODE 2. N/A 3. ANODE

STYLE 2: PIN 1. ANODE 2. N/A 3. CATHODE 4. ANODE

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